

Cleaning Liquid Composition for Electronic Device

Abstract:

5 [Purpose]

To provide a cleaning liquid composition that has excellent removability for metallic impurities and particulates, does not cause corrosion of Cu, and can clean a semiconductor substrate having copper wiring in a production process for an electronic device such as a semiconductor device.

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[Solution means]

A cleaning liquid composition for cleaning a semiconductor substrate having copper wiring, the cleaning liquid composition containing one or more types of basic compound containing no metal, and one or more types of phosphonic acid-based
15 chelating agent, and having a hydrogen ion concentration (pH) of 8 to 10.

No figures to accompany the abstract